Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

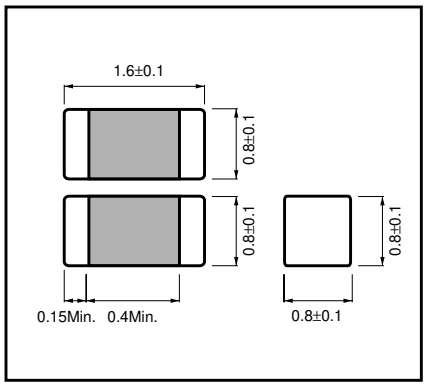
Multi-layer ceramic chip capacitors

MCH18 (1608 (0603) size, chip capacitor)

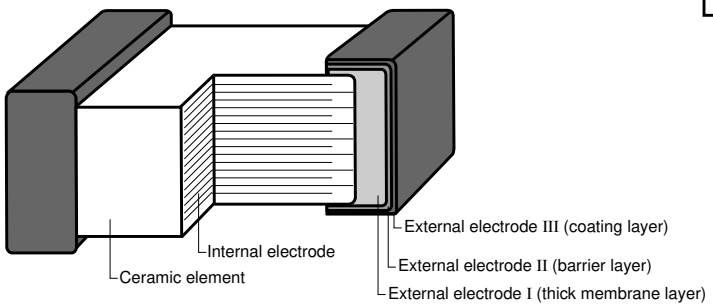
●Features

1) Small size (1.6 x 0.8 x 0.8 mm) makes it perfect for lightweight portable devices.
2) Comes packed either in tape to enable automatic mounting or in bulk cases.
3) Precise uniformity of shape and dimentions highly efficient automatic mounting.
4) Barrier layer and end terminations to improve solderability.

●External dimensions (Units : mm)



●Structure



●Product designation

Code	Product thickness	Packaging specifications	Reel	Basic ordering (pcs.)
K	0.8mm	Paper tape (width 8 mm, pitch 4 mm)	ϕ180mm (7in.)	4,000
L	0.8mm	Paper tape (width 8 mm, pitch 4 mm)	ϕ330mm (13in.)	16,000
C	0.8mm	Bulk case	–	15,000

Ree l(ϕ180,ϕ330mm) : compatible with EIAJ ET-7200A
Bulk case :compatible with EIAJ ET-7201A

Part No. — **Packaging style**

M	C	H	1	8	2	F	N	1	0	4	Z	K

Rated voltage

Code	Voltage
2	25V
3	16V
5	50V

Capacitance-temperature characteristics

Code	Code	Operating temperature (°C)	Temp. coefficient or percent change
A	C0G(C0G)	−55~+125	±30ppm/°C
CN	R	−55~+125	±15%
	B (X7R)	−25~+85 (−55~+125)	±10% (±15%)
FN	F (Y5V)	−25~+85 (−30~+85)	+30%,−80% (+22%,−82%)

Nominal capacitance: 3-digit designation according to IEC

Capacitance tolerance

Code	tolerance
C	±0.25pF (0.5 ~ 5pF)
D	±0.5pF (5.1 ~ 10pF)
J	±5% (11pF or more)
K	±10%
Z	+80%, −20%

●Capacitance range

For thermal compensation

Part number.		MCH18
Capacitance(pF)	Temperature characteristics	A (CG) (C0G)
	Rated voltage (V) / Tolerance	50
0.5	C (± 0.25pF)	■
0.75		■
1		■
1.1		■
1.2		■
1.3		■
1.5		■
1.6		■
1.8		■
2		■
2.2		■
2.4		■
2.7		■
3		■
3.3		■
3.6		■
3.9		■
4		■
4.3		■
4.7		■
5		■
5.1	D (± 0.5pF)	■
5.6		■
6		■
6.2		■
6.8		■
7		■
7.5		■
8		■
8.2		■
9		■
9.1		■
10		■
11	J (± 5%)	■
12		■
13		■
15		■
16		■
18		■
20		■
22		■
24		■
27		■
30		■
33		■
36		■
39		■
43		■
47		■
51		■
56		■
62		■
68		■
75		■
82		■
91		■
100		■

Part number.		MCH18
Capacitance (pF)	Temperature characteristics	A (CG) (C0G)
	Rated voltage (V) / Tolerance	50
110	J (± 5%)	■
120		■
130		■
150		■
160		■
180		■
200		■
220		■
240		■
270		■
300		■
330		■
360		■
390		■
430		■
470		■
510		■
560		■
620		■
680		■
750		■
820		■
910		
1,000		

■ Product thickness (mm) 0.8 ± 0.1

Ceramic capacitors

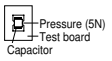
High dielectric constant

Part number		MCH18				
Capacitance(pF)	Temperature characteristics	CN (R) (B) (X7R)		FN (F) (Y5V)		
	Rated voltage (V)	50	25	50	25	16
	Tolerance	K (±10%)		Z (+80%, −20%)		
220 270 330		▨				
390 470 560		▨				
680 820 1,000		▨		▨		
1,200 1,500 1,800		▨				
2,200 2,700 3,300		▨		▨		
3,900 4,700 5,600		▨		▨		
6,800 8,200 10,000 (0.01µF)		▨		▨		
12,000 15,000 18,000		▨				
22,000 27,000 33,000		▨	▨	▨		
39,000 47,000 56,000			▨	▨		
68,000 82,000 100,000 (0.1µF)			▨ ▨		▨	
120,000 150,000 180,000						
220,000 270,000 330,000						▨
390,000 470,000 560,000						
680,000 1,000,000 (1µF) 1,200,000						
1,500,000 1,800,000 2,200,000						

▨ Product thickness (mm) 0.8 ± 0.1

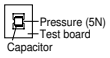
●Characteristics

Class 1 (For thermal compensation)

Item \ Temperature characteristics		A (CG) (C0G)	Test methods / conditions (based on JIS C 5102)
Operating temperature		−55°C ~ +125°C	———
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 and paragraph 9 Measured at room temperature and standard humidity. 1000pF or less Measurement frequency : 1± 0.1MHz Measurement voltage : 1± 0.1Vrms. Over 1000pF Measurement frequency : 1± 0.1kHz Measurement voltage : 1± 0.1Vrms.
Dissipation factor (tan δ)		100 / (400 + 20C)% or less (Less than 30 pF) 0.1% or less (30 pF or larger)	
Insulation resistance (IR)		10,000MΩ or 500MΩ·μF , whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 ± 5s.
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 300% of the rated voltage for 1 to 5s then measure.
Temperature characteristics		Within 0 ± 30ppm / °C	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11.2 Apply 5N for 10 ± 1s in the direction indicated by the arrow. 
Resistance to vibration	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2), and measured 24 ± 2 hrs. later. 
	Rate of capacitance change	Must be within initial tolerance.	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
Solderability		At least 3 / 4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature : 235 ± 5°C Soldering time : 2 ± 0.5s
Resistance to soldering heat	Appearance	There must be no mechanical damage.	Based on paragraph 8.14 Soldering temperature : 260 ± 5°C Soldering time : 5 ± 0.5s Preheating : 150 ± 10°C for 1 to 2 min.
	Rate of capacitance change	± 2.5% or ± 0.25 pF , whichever is larger.	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF , whichever is smaller	
	Withstanding voltage	The insulation must not be damaged.	
Temperature cycling	Appearance	There must be no mechanical damage.	Based on paragraph 9.3 Number of cycles : 5 Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 2.5% ± 0.25 pF , whichever is larger.	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	
	Insulation resistance	10,000MΩ or 500MΩ·μF , whichever is smaller	
Humidity load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9 Test temperature : 40 ± 2°C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 7.5% or ± 0.75 pF , whichever is larger.	
	Dissipation factor (tanδ)	0.5% or less	
	Insulation resistance	500MΩ or 25MΩ·μF , whichever is smaller	
High-temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10 Test temperature : Max. operating temp. Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs. Capacitance measured after 24 ± 2 hrs.
	Rate of capacitance change	± 3.0% or ± 0.3 pF , whichever is larger.	
	Dissipation factor (tanδ)	0.3% or less	
	Insulation resistance	1,000MΩ or 50MΩ·μF , whichever is smaller	

Ceramic capacitors

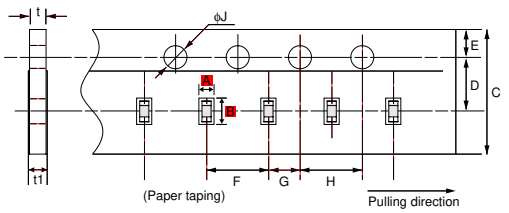
Class 2 (High dielectric constant)

Item \ Temperature characteristics		CN (R) (B) (X7R)	FN (F) (Y5V)	Test methods/conditions (based on JIS C 5102)
Operating temperature		−55°C ~ +125°C	−30°C ~ +85°C	————
Nominal capacitance (C)		Must be within the specified tolerance range.		Based on paragraph 7.8 Measured at room temperature and standard humidity, Measurement frequency: 1 ± 0.1 kHz Measurement voltage : 1.0 ± 0.2 Vrms.
Dissipation factor (tanδ)		2.5% or less (when rated voltage is 16V: 3.5% or less)	5.0% or less (when rated voltage is 16V: 7.5% or less)	
Insulation resistance (IR)		10,000 MΩ or 500 MΩ · μF, whichever is smaller		Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 ± 5s.
Withstanding voltage		The insulation must not be damaged.		Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measure.
Temperature characteristics		Within ± 15%	+ 22, + 82%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.
Terminal adherence		No detachment or signs of detachment		Based on paragraph 8. 11. 2. Apply 5N for 10 ± 1s in the direction indicated by the arrow. 
Resistance to vibration	Appearance	There must be no mechanical damage.		Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2), and measured 48 ± 4 hrs. later. 
	Rate of capacitance change	Must be within initial tolerance.		
	Dissipation factor (tanδ)	Must satisfy initial specified value.		
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.		Based on paragraph 8. 13 Soldering temperature: 235 ± 5°C Soldering time : 2 ± 0.5s
Resistance to soldering heat	Appearance	There must be no mechanical damage.		Based on paragraph 8. 14. Soldering temperature: 260 ± 5°C Soldering time : 5 ± 0.5s Preheating : 150 ± 10°C for 1 to 2 min.
	Rate of capacitance change	Within ± 5.0%	Within ± 20.0%	
	Dissipation factor (tanδ)	Must satisfy initial specified value.		
	Insulation resistance	10,000MΩ or 500MΩ · μF, whichever is smaller		
	Withstanding voltage	The insulation must not be damaged.		
Temperature cycling	Appearance	There must be no mechanical damage.		Based on paragraph 9.3 Number of cycles : 5 Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	Within ± 7.5%	Within ± 20.0%	
	Dissipation factor (tanδ)	Must satisfy initial specified value.		
	Insulation resistance	10,000MΩ or 500MΩ · μF, whichever is smaller		
Humidity load test	Appearance	There must be no mechanical damage.		Based on paragraph 9.9 Test temperature: 40 ± 2°C Relative humidity: 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	± 12.5% or less	Within ± 30.0%	
	Dissipation factor (tanδ)	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	
	Insulation resistance	500MΩ or 25MΩ · μF, whichever is smaller		
High-temperature load test	Appearance	There must be no mechanical damage.		Based on paragraph 9.10 Test temperature: Max. operating temp. Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs. Capacitance measured after 48 ± 4 hrs.
	Rate of capacitance change	Within ± 10.0%	Within ± 30.0%	
	Dissipation factor (tanδ)	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)	
	Insulation resistance	1,000MΩ or 50MΩ · μF, whichever is smaller		

●Packaging specifications

(Units : mm)

Taping

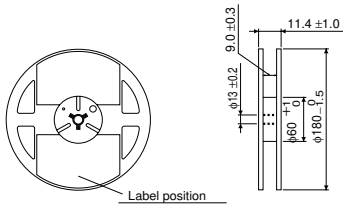


Symbol	C	D	E	F	G	H	J	t	t1
Dimensions	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.1	ϕ1.5 $^{+0.1}_{0}$	1.05 MAX.	1.2 MAX.

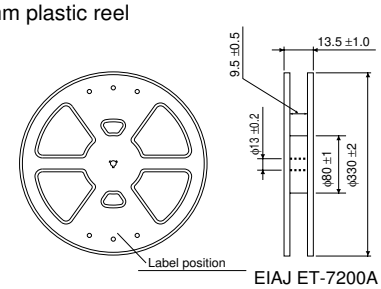
Size \ Symbol	A	B
1608	1.0 ±0.1	1.8 ±0.1

Reel

ϕ180 mm plastic reel

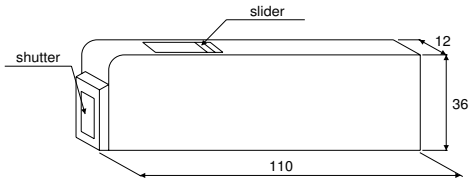


ϕ330 mm plastic reel



EIAJ ET-7200A compliant

Bulk case



EIAJ ET-7201A compliant | **MCH18** | 15,000pcs / case

●Electrical characteristics

■ A (C0G) Characteristics

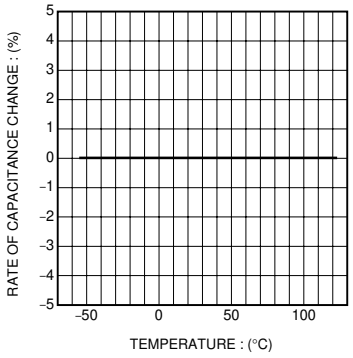


Fig.1 Capacitance - temperature characteristics

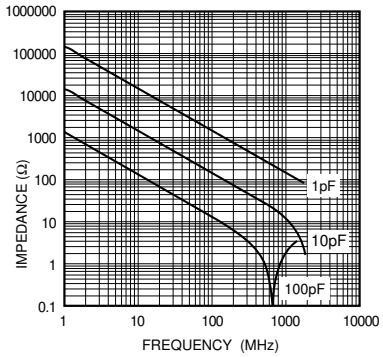


Fig.2 Impedance - frequency characteristics

■CN (X7R) Characteristics

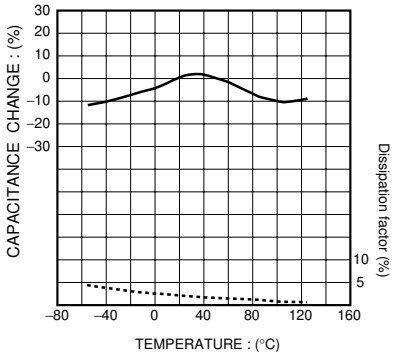


Fig.3 Capacitance - temperature characteristics

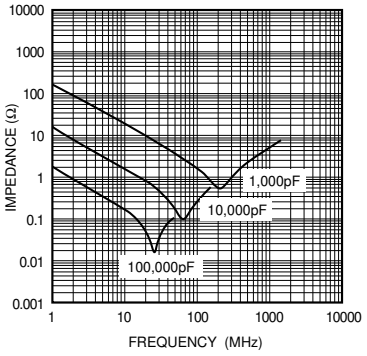


Fig.4 Impedance - frequency characteristics

■FN (Y5V) Characteristics

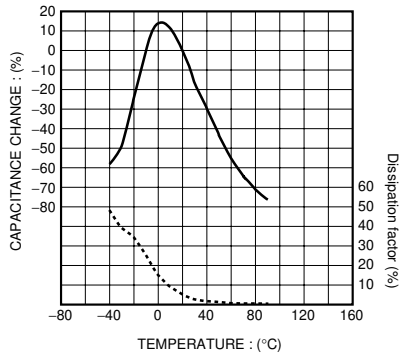


Fig.5 Capacitance - temperature characteristics

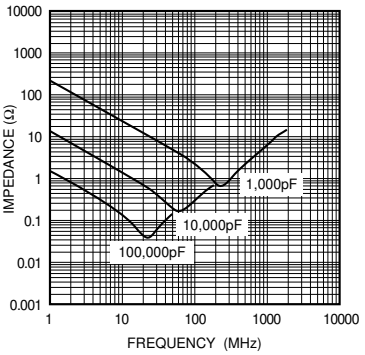


Fig.6 Impedance - frequency characteristics

■ Temperature cycling test

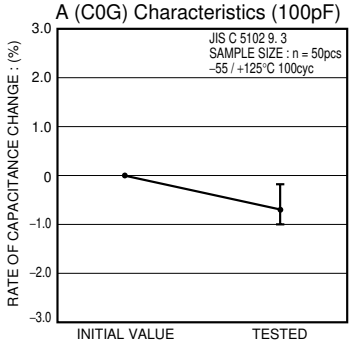


Fig.7 Rate of capacitance change

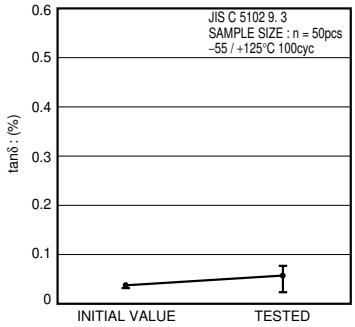


Fig.8 tanδ

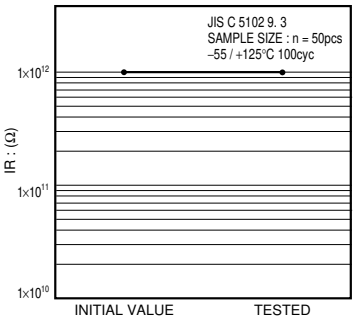


Fig.9 Insulation resistance

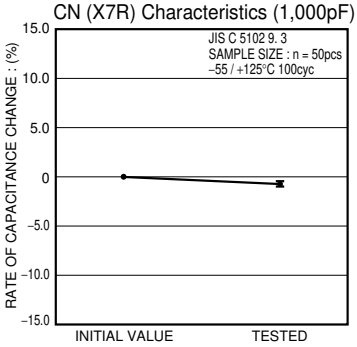


Fig.10 Rate of capacitance change

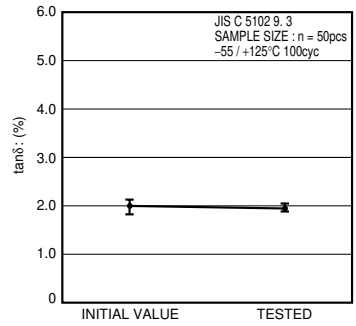


Fig.11 tanδ

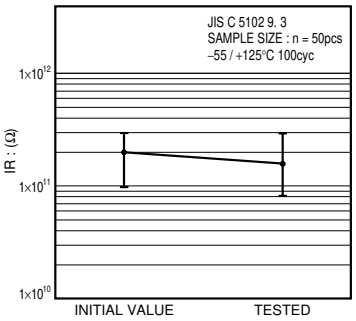


Fig.12 Insulation resistance

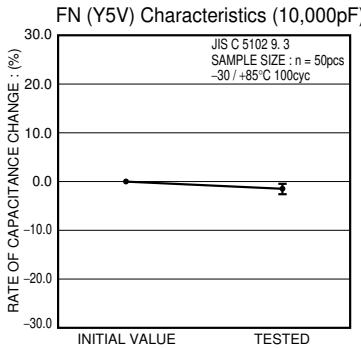


Fig.13 Rate of capacitance change

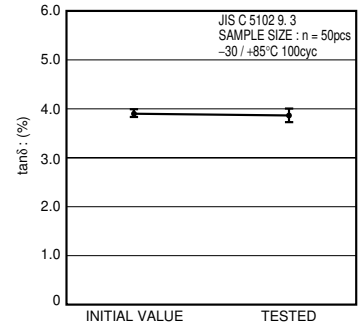


Fig.14 tanδ

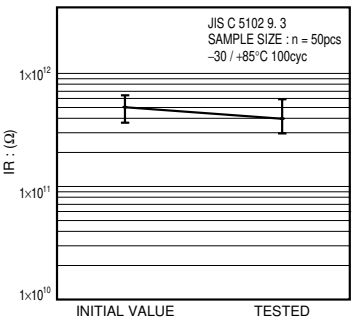


Fig.15 Insulation resistance

■ High-temperature load test

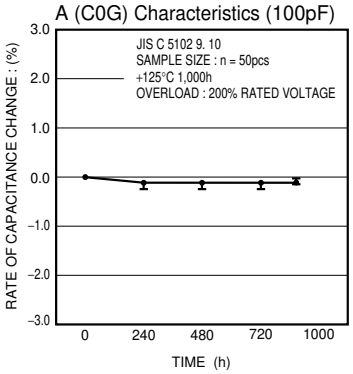


Fig.16 Rate of capacitance change

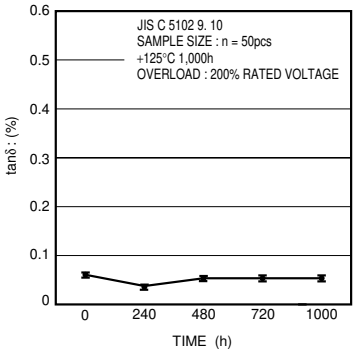


Fig.17 tanδ

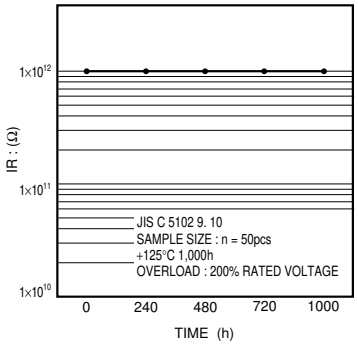


Fig.18 Insulation resistance

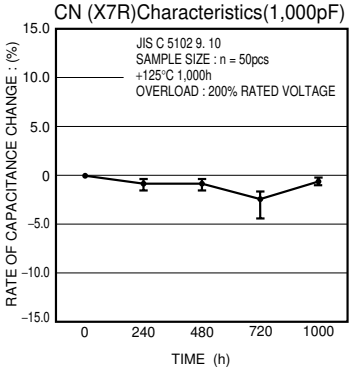


Fig.19 Rate of capacitance change

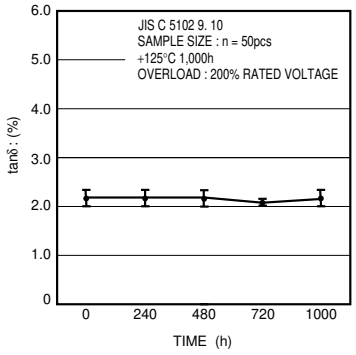


Fig.20 tan δ

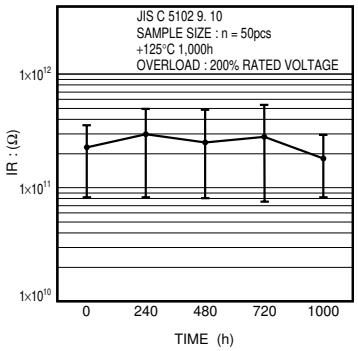


Fig.21 Insulation resistance

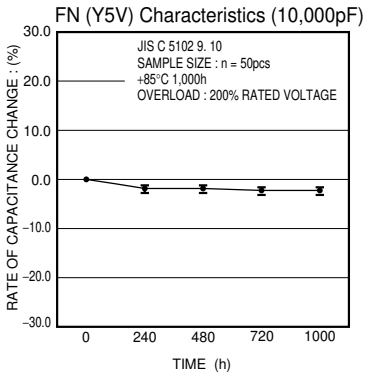


Fig.22 Rate of capacitance change

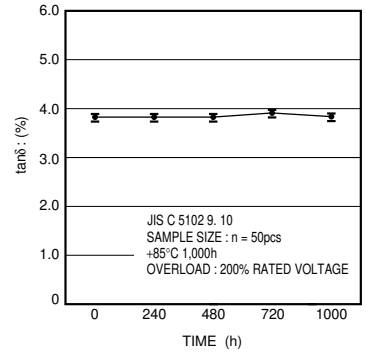


Fig.23 tanδ

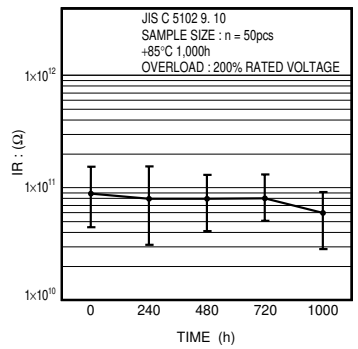


Fig.24 Insulation resistance

■ Humidity load test

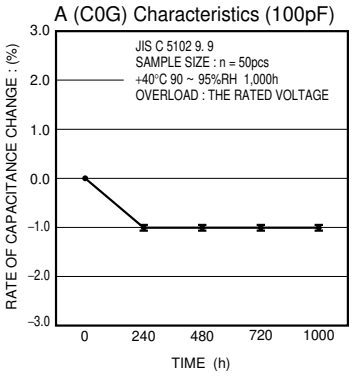


Fig.25 Rate of capacitance change

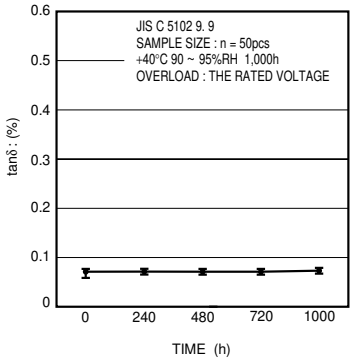


Fig.26 tan δ

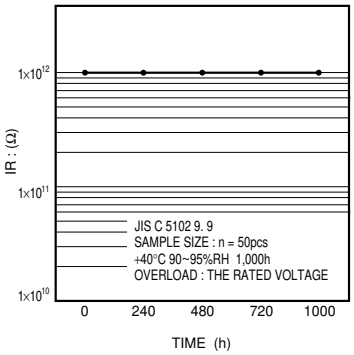


Fig.27 Insulation resistance

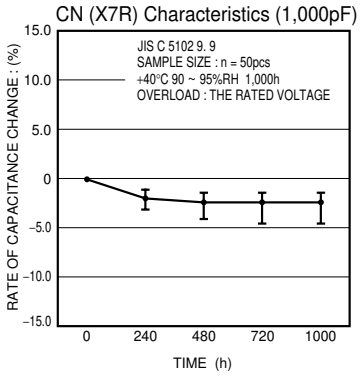


Fig.28 Rate of capacitance change

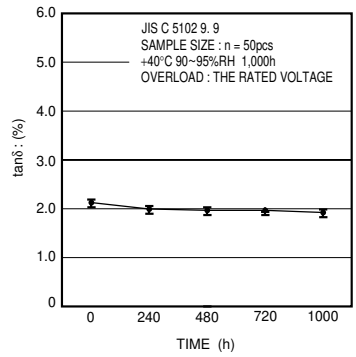


Fig.29 tanδ

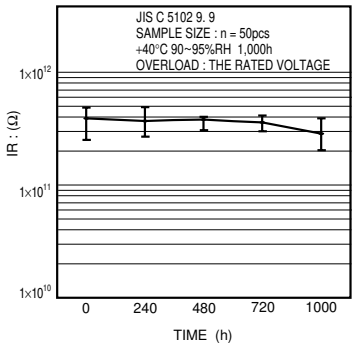


Fig.30 Insulation resistance

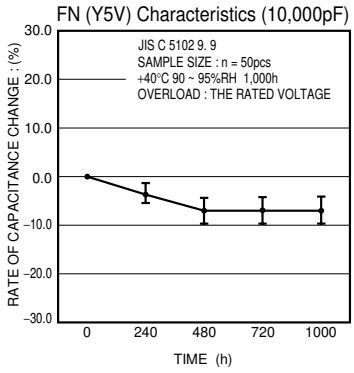


Fig.31 Rate of capacitance change

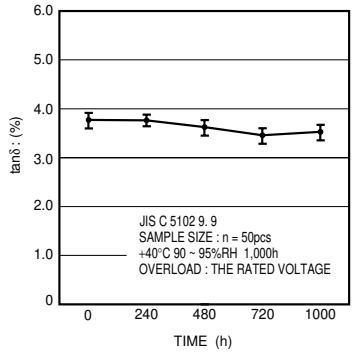


Fig.32 tanδ

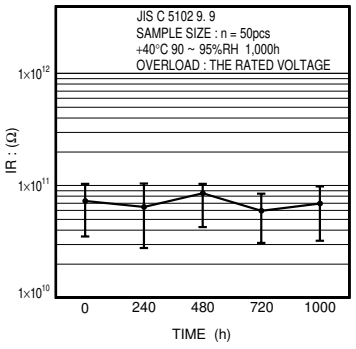


Fig.33 Insulation resistance